

Sandia's HPC Platform Strategy: Preparation for Exascale

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Outline

- **Co-design**
- **DARPA/UHPC X-caliber project**
- **Key enabling capabilities**
- **Leverage Sandia's MESA (Microsystems and Engineering Sciences Application) capabilities**
- **Industry collaborations**
- **Sandia's collaboration with Micron Technology**
- **Keys to realizing Exascale computing**

Co-design

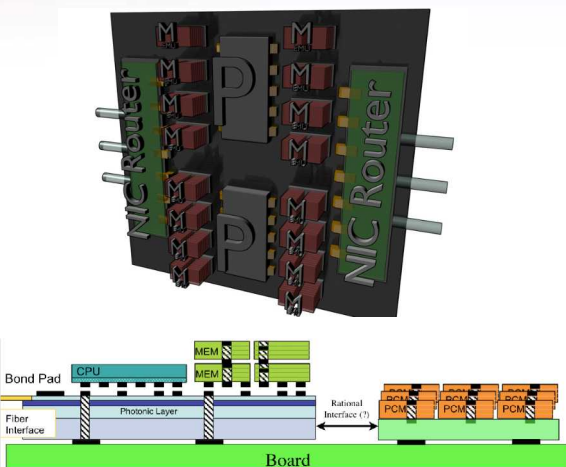
- **Lessons from the embedded computing community**
 - Working with Prof. Sharon Hu, University of Notre Dame, one of the pioneers of co-design for embedded computing design
 - Optimization is based on partitioning the work among different elements of the embedded system to minimize energy consumption
- **The traditional focus for HPC is to minimize wall clock time**
 - The objective function for Exascale HPC will be to optimize based on some weighted average between minimizing time to solution and minimizing energy per solution
- **Ongoing and New Co-design efforts – see Hemmert/Rodrigues' talk**
 - DARPA/UHPC X-caliber project
 - Work with LANL on the ACES – Cray Advanced Interconnection Network project – see Hemmert's talk
 - Participant in two of the recently announced DOE/ASCR Exascale Co-design Centers:
 - Combustion ECDC – Sandia led
 - ExMatEx CDC – LANL led



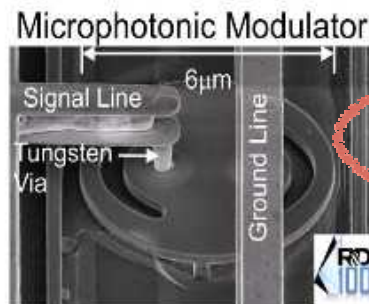
X-caliber – Ubiquitous HPC Proposal

Sandia National Laboratories, LexisNexis, Micron Technologies,
LSU, USC/ISI, Notre Dame, UIUC

With support from NNSA/ASC, DOE/ASCR, DoD and Open Source Communities: e.g., SST, Trilinos



High Level Packaging Strawman



"Ultralow-Power Silicon Microphotonic Communications Platform"
2009 R&D100 Award Winner

Our Process/Approach

- Develop X-caliber architecture with multi-dimensional co-design to analyze and evaluate a rich suite of innovative technologies for HPC systems and applications
- Apply system simulators and prototype testbeds to quantify the performance of extreme-scale applications on conceptual architecture designs
- Adopt open innovation philosophy to grow and leverage ideas from the IT community and beyond

Cultivate Strategic Linkages

- DOE/ASCR, NNSA/ASC, DOE Exascale Initiative
- Other DoD, DOE/LDRD

Key Innovations

- Memory-centric approach to HPC design
- The system is memory that produces computation, not processors talking to dumb memory
- ParallelX execution model allows movement of computation to data in ways that minimize the energy consumption
- Exploit infrastructure for global control flow
- Adaptive runtime and OS to allow computation migration in response to component failures
- Adaptivity also enables "sprint mode" operations in the processor, memory and network to support transient high power operation in return for lower global energy usage

Expected Impact

- Develop a conceptual design to overcome the energy efficiency, dependability and programmability challenges of the five UHPC challenge problems
- Establish collaborative partnerships both internal and external to X-caliber/UHPC



X-caliber Leadership



- **Uniqueness – deep vertical integration**
 - A technology foundation that spans – device physics, semiconductor fabrication, microelectronics packaging, HPC architecture design, system software, algorithm and application developers/users
- **While Sandia is the lead, we assembled a large diverse team in acknowledgment of Joy's Law**
 - *No matter who you are, most of the smartest people work for someone else*
- **Sandia is a *Lead User* – able to innovate in ways that are not constrained by Business Models**
 - *Lead Users are firms or individual consumers that expect to benefit from **using** a product or service. In contrast, manufacturers expect to benefit from **selling** a product or service. – Eric von Hippel*
- **Business Models are important: Sandia has first-hand understanding of the differences between:**
 - First of a Kind
 - One of a Kind

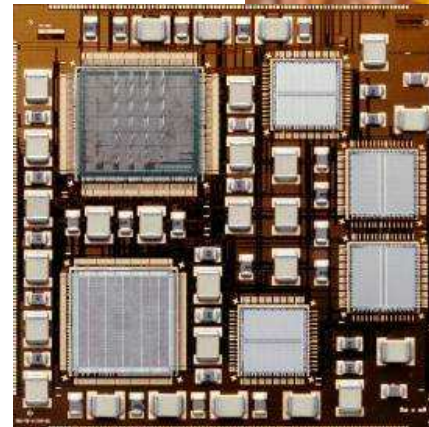


Key Enabling Capabilities

- SST Open Framework for HPC architectural simulation
 - see Rodrigues' talk
- Mantevo Miniapps – see Barrett's talk
- Codesign Roundtable
 - Applications
 - Algorithms
 - System Software
 - Architectures
 - Microelectronics design and fabrication capability
- Experimental architecture testbeds

Leverage MESA Capabilities

- **Key areas of collaboration:**
 - Processor/Memory design
 - 3D Integration and Quilt Packaging
 - Optical Interconnects
- **Sandia's Microsystems Center is one of the heaviest users of IBM's trusted foundry**
- **Recent design submission history**
 - FY06-08: 14 Design Submissions (130nm, 90nm nodes)
 - FY09-10: 16 Design Submissions (130nm, 90nm, 65nm, 45nm nodes)



Industry Collaborations

Cultivate strategic partnerships

- Intel – Umbrella CRADA
- IBM – Trusted Foundry Work, informatics
- Cray – CRADA for informatics & ACES D&E project
- Oracle (Sun) – **See Noe's talks on Red Sky**
- Micron Technology – CRADA for ECC development

How do we encourage industry to pursue the revolutionary approaches needed to address Exascale?

- Growing expertise in computer engineering and architecture – important to collaborate with industry as partners
- This expertise compliments our application, algorithm, and system software developers to be able to co-design and develop prototypes to implement and experiment with revolutionary models of computation
- We are also making a sustained investment in the open development of the SST simulation framework, and Mantevo mini-application proxies
- With our Microsystems design and fabrication capability, Sandia is also able to create proof of concept prototypes and hardware artifacts

Summary of Micron-Sandia Interactions

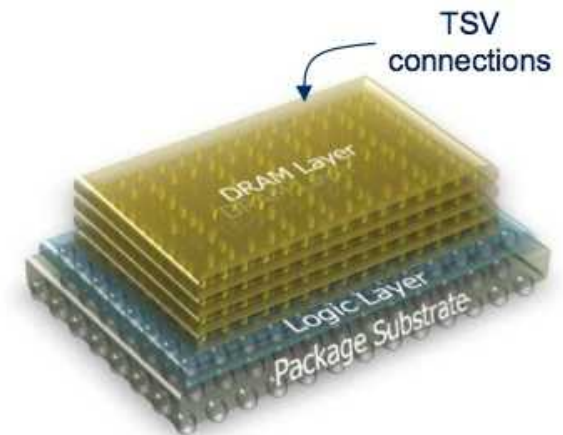
Activity	Outputs
Kickoff Meeting	Micron-Sandia Collaboration Begins (July'06)
Foundation for Discussions	2-way NDA (Nov'07)
Advanced Memory for DOE Architectures	Simulations, Papers, PIM LDRD Effort, ASC/CSSE L2 Milestone: Evaluate Advanced Memory Subsystems – 4Q-FY10
IAA Activities	Dean Klein is a member of the IAA Advisory Board IAA Workshop on Memory Opportunities for HPC (Jan'08) IAA Workshop on HPC Architectural Simulation (Sept'09)
Collaborations with other agencies	Alignment of ASC/CSSE, DoD/ACS, & IAA support to Integrate U-MD's Memory Simulator (DRAMsim & eBOBsim) with Sandia's SST
Proposal Partnerships	DARPA/UHPC X-caliber, DOE/ASCR Data Movement Dominates
CRADA – established July'10	Micron-Sandia collaboration to analyze advanced concepts for error correction in advanced memory designs – Patent Application filed, May '11, <i>Automated discovery of optimal, symbol-based SECDED codes</i>

• Technical Exchanges from July 2006 - Present

- Approximately 30 face-to-face technical meetings
- Catalyst for Collaboration with other DOE/NNSA labs, DoD, and Universities

New Micron Technology Development and Engineering Project

- Based on our long-term collaboration, Sandia is helping NNSA/ASC establish a Cooperative Agreement with Micron Technology
- On behalf of NNSA/ASC and DOE/ASCR, Sandia is responsible for technical oversight of, and collaboration with Micron on this project
- Sandia working with Micron to define the technical scope – the project has four major parts:
 - Construction of the simulation infrastructure
 - Design explorations, focused on sets of in-memory operations to be evaluated, simulated, and analyzed
 - FPGA prototyping work of ideas that are identified as candidates for inclusion in future HMC parts
 - Research into improved low energy signaling and topologies



*Functioning prototypes in silicon
TODAY*

Keys to Realizing Exascale Computing

- **Improving data movement performance / efficiency**
 - Both intra-node and inter-node
- **Developing a Co-design methodology for HPC**
 - Including the development of the objective function that balances minimizing time to solution with minimizing energy to solution
- **Providing processor, memory, and interconnection network designers with insights from application users/developers, system software developers on how best to use the additional transistors that Moore's Law will continue to provide**
- **Significant investment in new application development**
 - Both funding and time